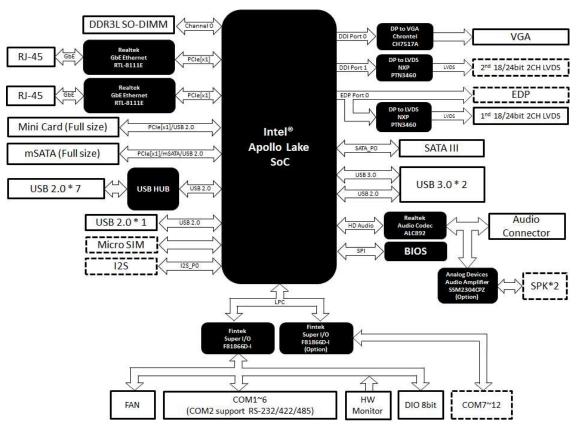


## **GENE-APL7 A1.0\_0\_1**

## **Sub Compact Board**

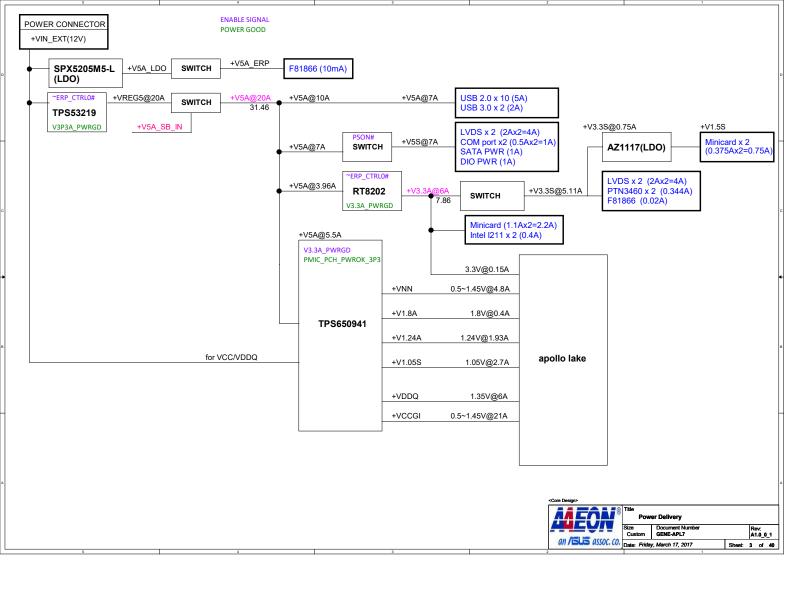


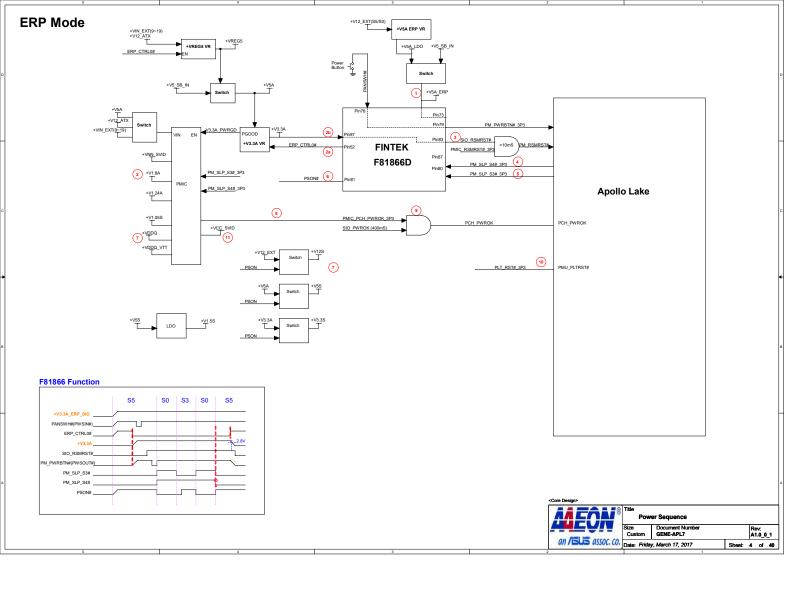
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2	SYSTEM SETTINGS
3	POWER DELIVERY
4	POWER SEQUENCE
5	SOC_DDR
6	SOC_DISPLAY
7	SOC_SATA_PCIE_USB
8	SOC_LPC_SPI_EMMC_SD
9	SOC_SMBUS_GPIO
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34	POWER_+V12A
35	STANDBY POWER
36	SYSTEM POWER
37	POWER INPUT,MISC
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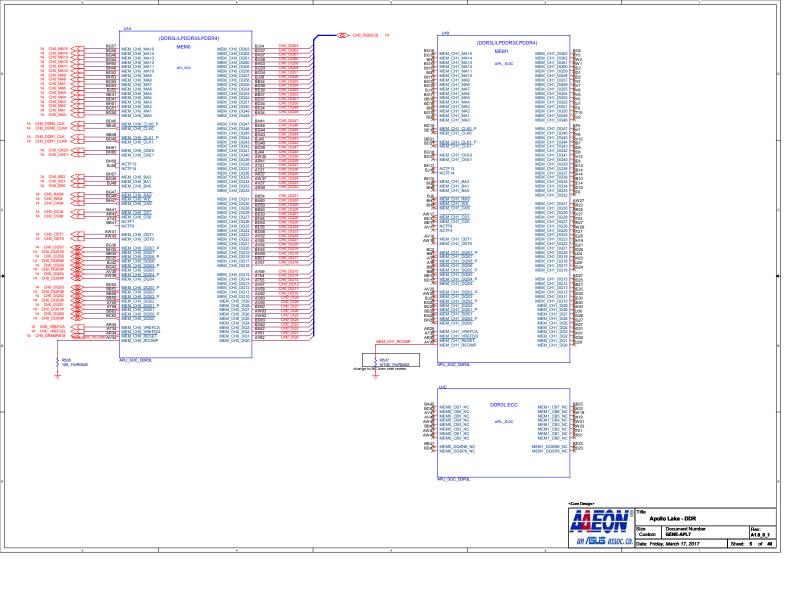
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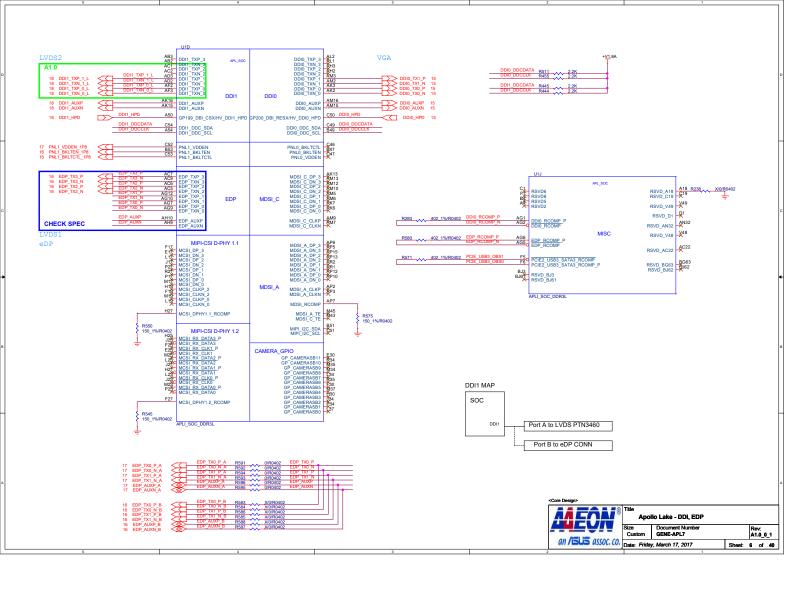
Production Line : Sub.ESB.AASM

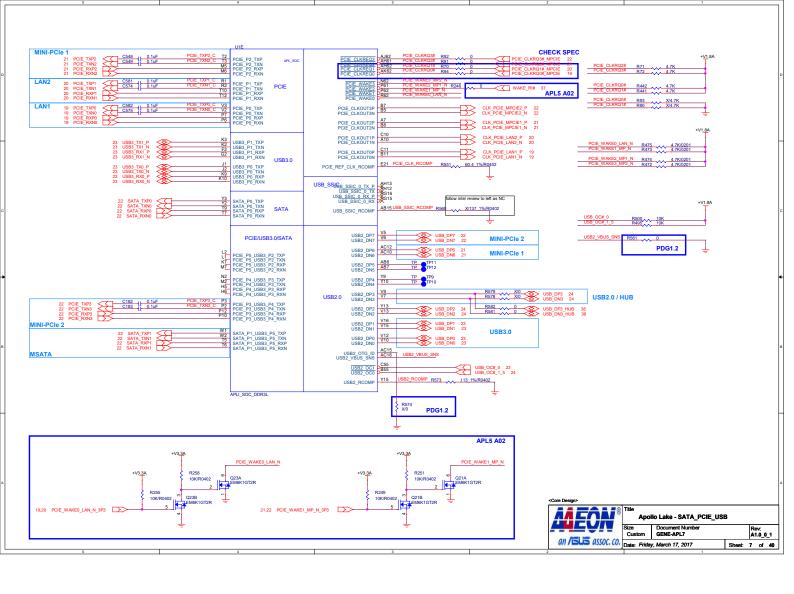
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PCB Footprints	SOC GPIO Pins :	F81866D GPIO Pins	:		F81866D GI	PIO Pins :			
Impedence 550hm +/-15%.  Layer 1: Component  Layer 2: Signal  Layer 3: Signal  Layer 6: Signal  Layer 7: GND  Layer 7: GND  Layer 8: Solder	Name	Name	1.   1.   1.   1.   1.   1.   1.   1.	Function  EEPP CTRLIS  EEPP CTRLIS  EPP CTRLIS  PM SILS WARNIS  AN TOTAL PM SILS WARNIS  WE DISABLES  ATK AT TRAP  WOT SILS  ATK AT TRAP  WOT SILS  ATK AT TRAP  DATE OF COLUMN SILS  ATK ATT TRAP  DATE OF COLUMN SILS  ATK ATT TRAP  DATE OF COLUMN SILS  ATK ATT TRAP  DO TO THE SILS  RESE  DO TRASS  RESE  RESE  RESE  RESE  DO TRASS  DO TRASS  RESE  DO TRASS  DO TRASS  DO TRASS  DO TRASS  DO TRASS  RESE  DO TRASS  RESE  DO TRASS  RESE  DO TRASS  DO TRASS  RESE  DO TRASS  RESE  RES  RES	Name  GP1001  GP1002  GP1002  GP1003  GP1003  GP1003  GP1003  GP1004  GP1011  GP1011  GP1013  GP1013  GP1013  GP1014  GP1015  GP1015  GP1016  GP1016  GP1017  GP1023  GP1023  GP1024  GP1024  GP1025  GP1025  GP1026  GP1026  GP1027  GP1028	Tolerance  9V	V-883/   V	Nation	1. diver mode
PCB STACK: Impedence 550hm 4/15%.  Layer 1: Component Layer 2: GRD Layer 3: Signal Layer 4: Signal Layer 6: Signal Layer 6: Signal Layer 7: GRD Layer 8: Solder  Tile System Settlings	GP0 (2   68h   Ph0460 Shree   C0h   Ph0460 Shree   C0h   C	GP1092 St. GP1093 St. GP1093 St. GP1093 St. GP1094 St. GP1094 St. GP1094 St. GP1094 St. GP1097 St.	V	LVDSS EN	G0064 G0064 GP1066 GP1066 GP1066 GP1071 GP1071 GP1077 GP1077 GP1077 GP1077 GP1078	5V 5V 5V 8V 8V 8V 5V 5V 5V 5V 5V 5V 5V 5V 5V 5V 5V 5V 5V	3VCC 3VCC 1 VSB3V VBAT 1 VSB3V 3VCC	Native	
Custom Generaliz Atla 0 -1  Al 10 -1  Al 20 -1  Al 20 -1  Al 20 -1  Al 30 -1	Impedence 550hm +/-15%.	GPOSY S	V 9/CG Selve	100.1	GPIO28	ore Designs	Title	System Settings    Document Number   Document Number	Rev.   A1.0_0_1

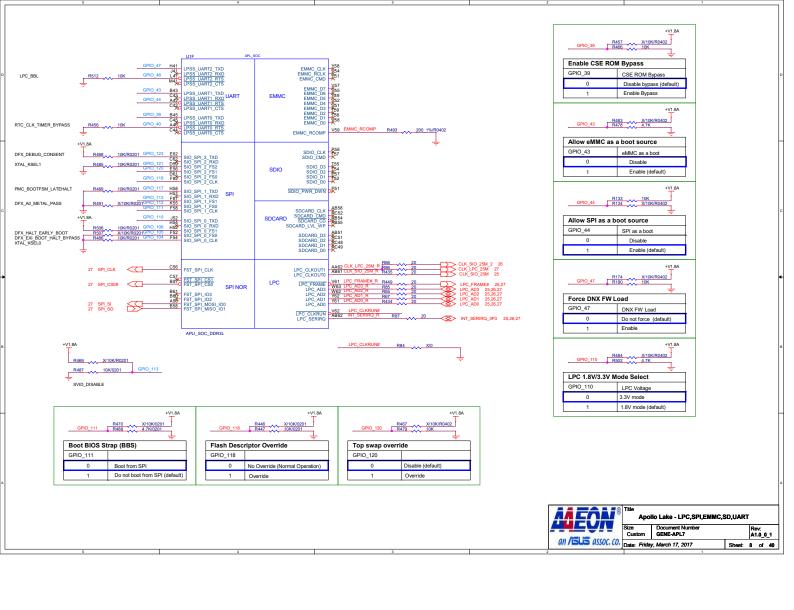


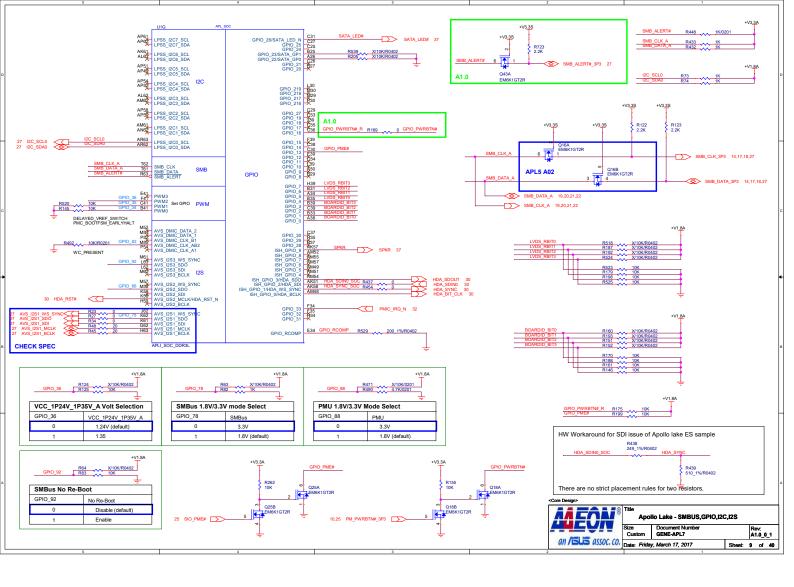


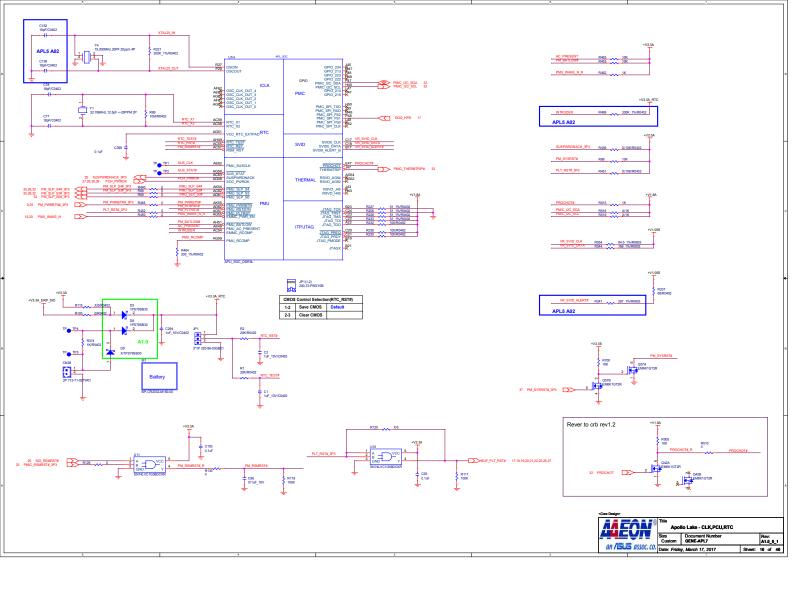


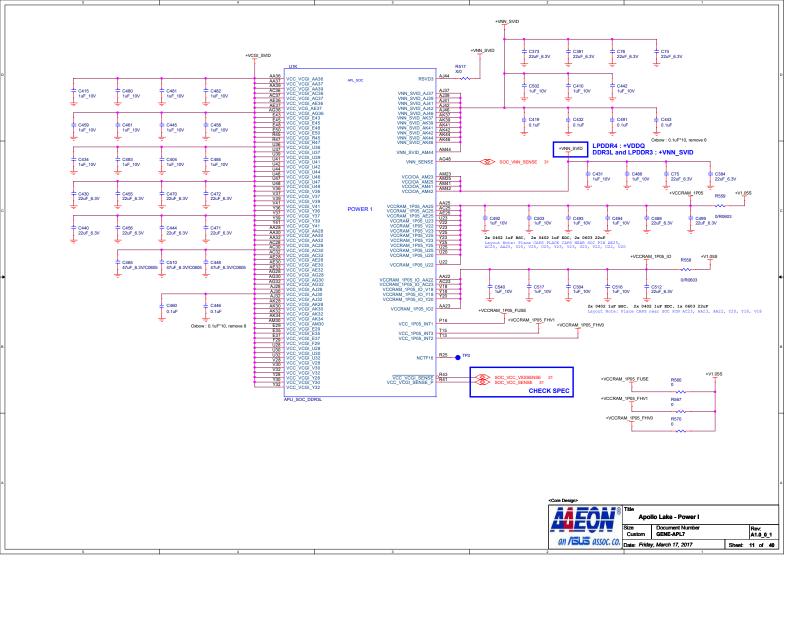


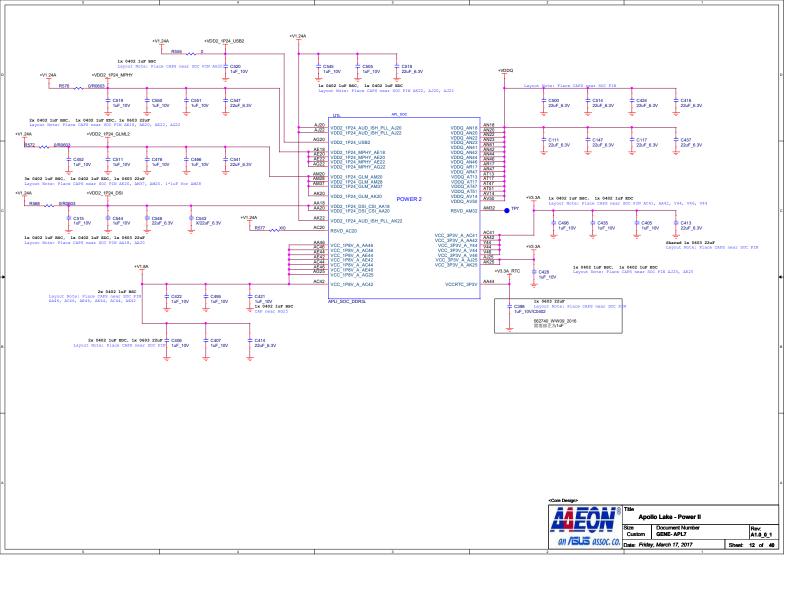


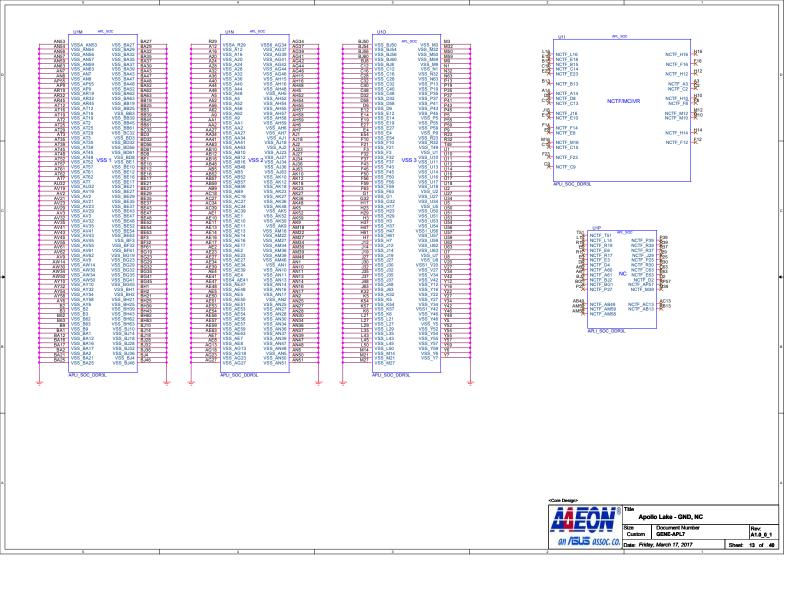


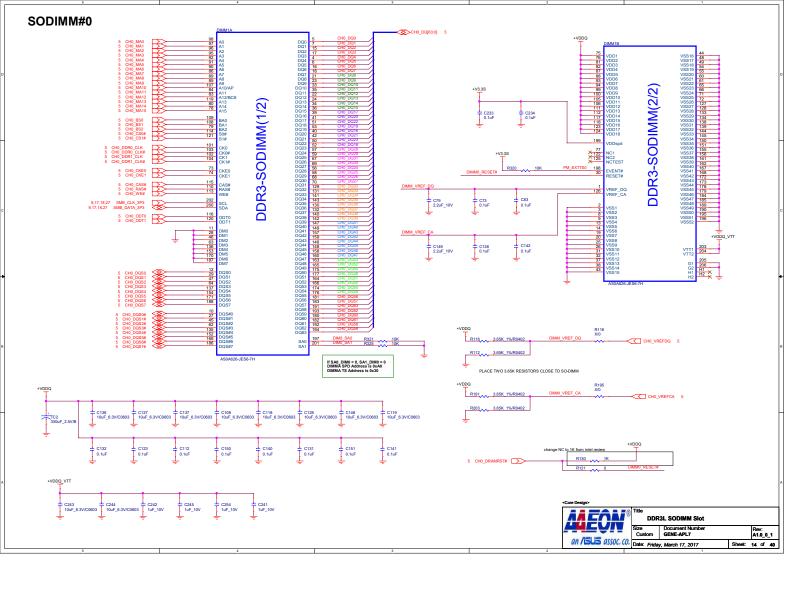


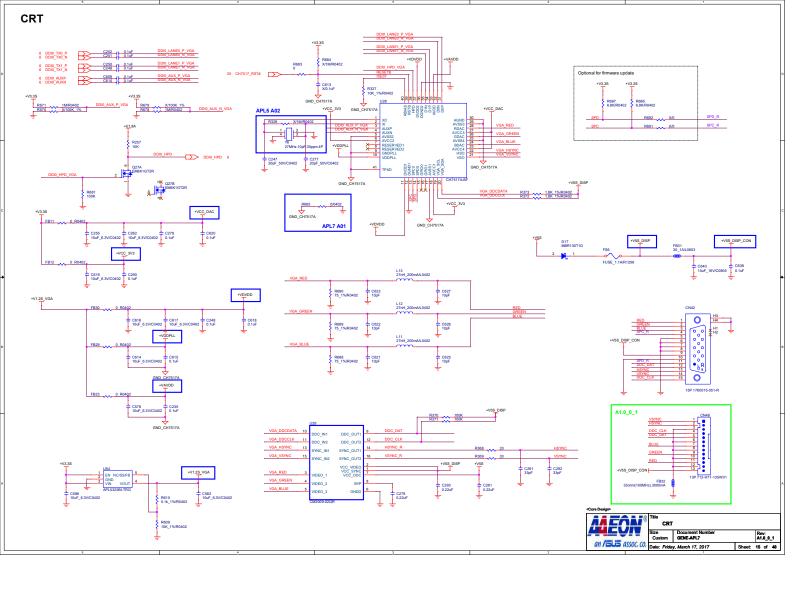


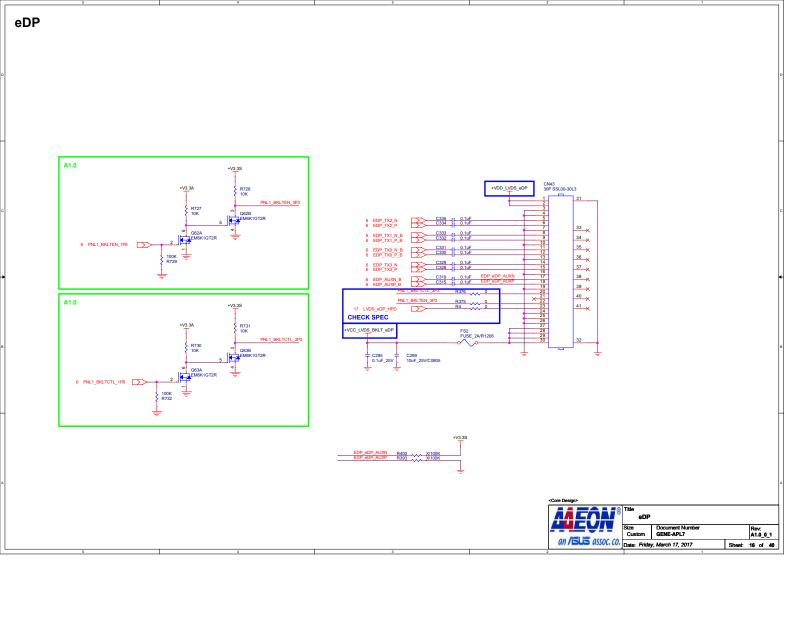


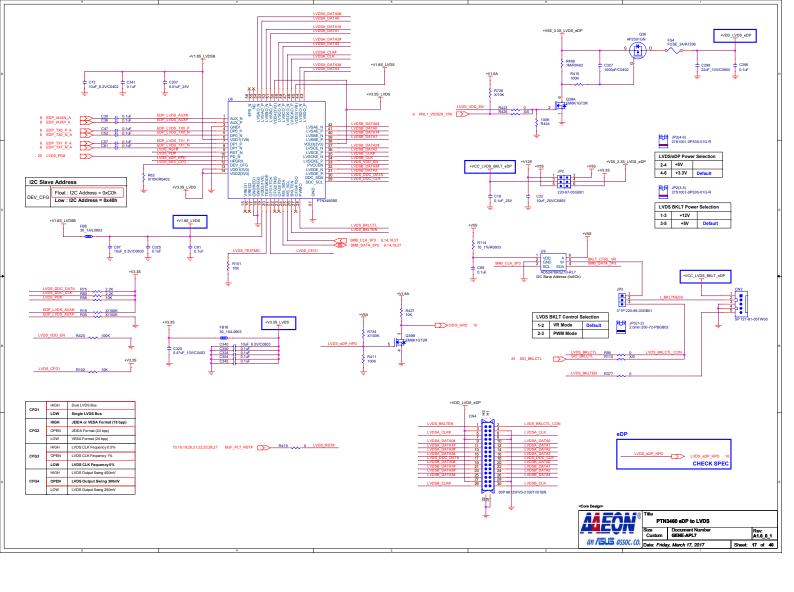


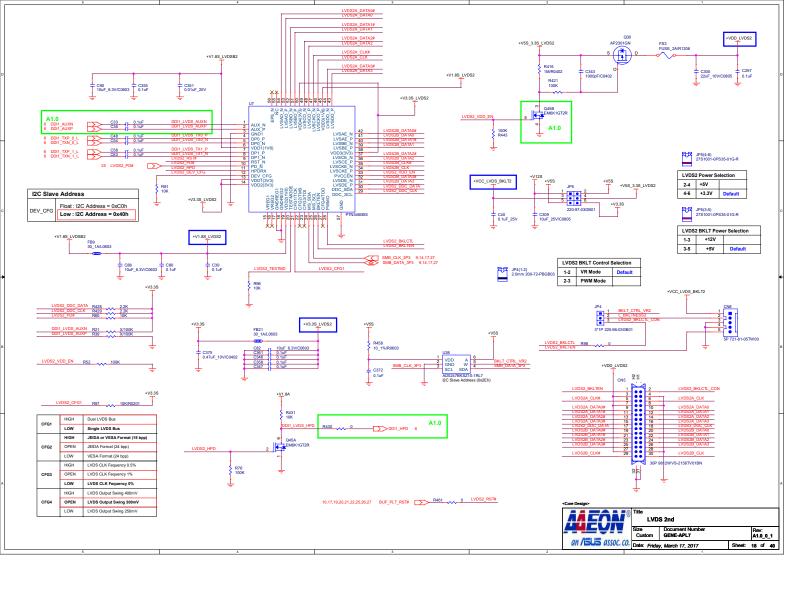


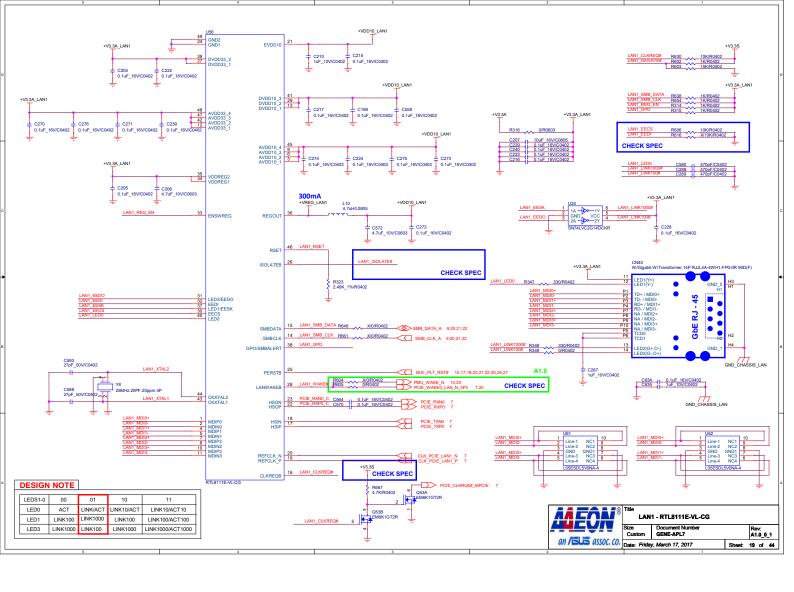


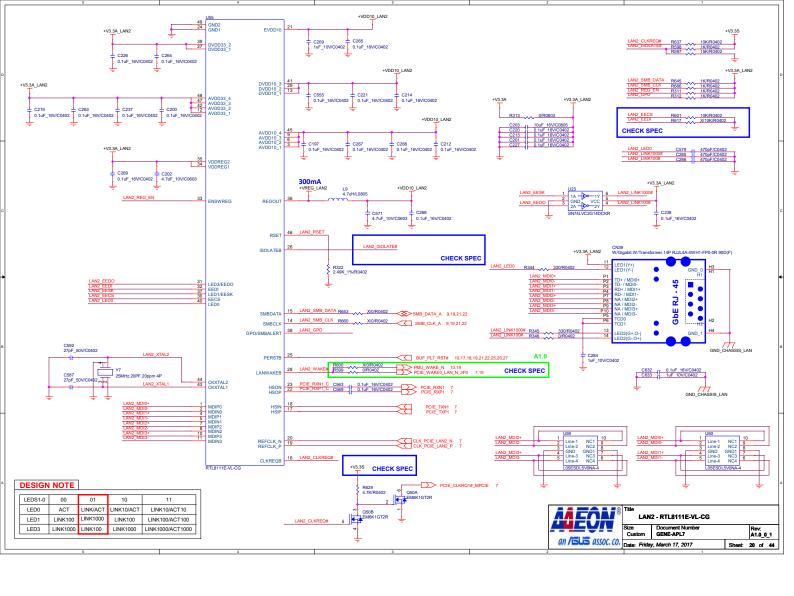


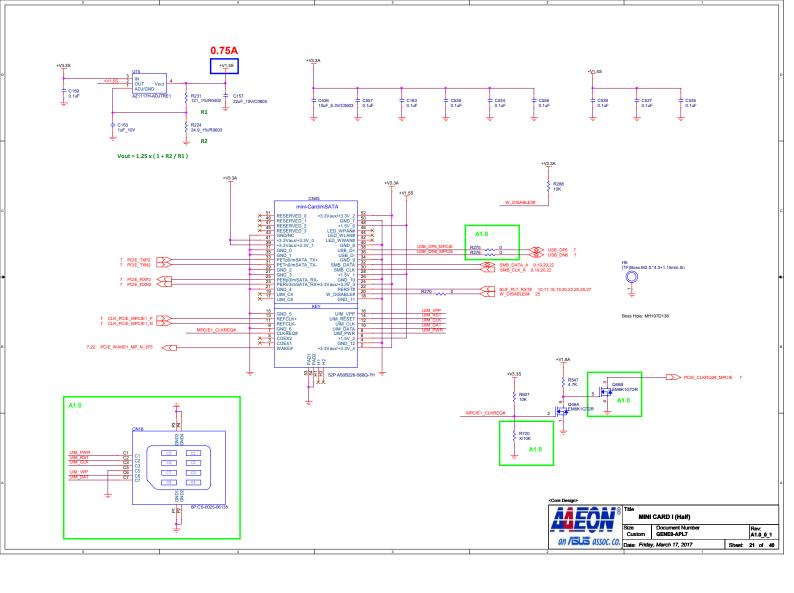


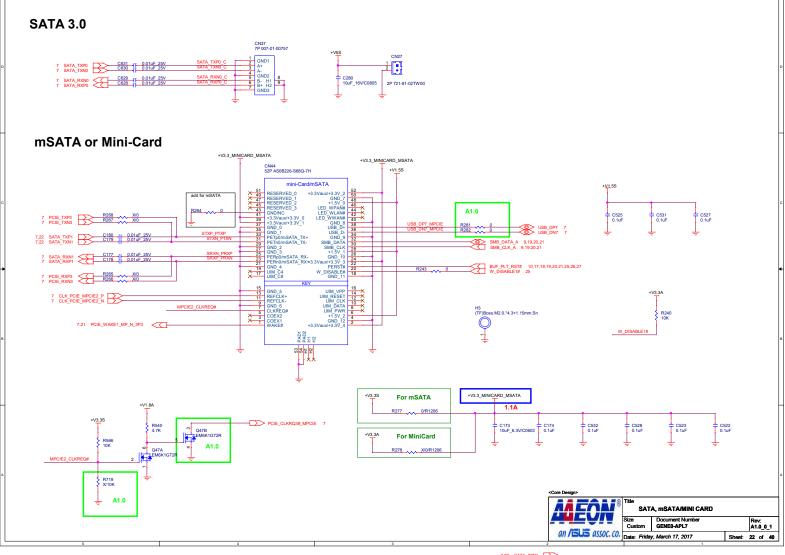




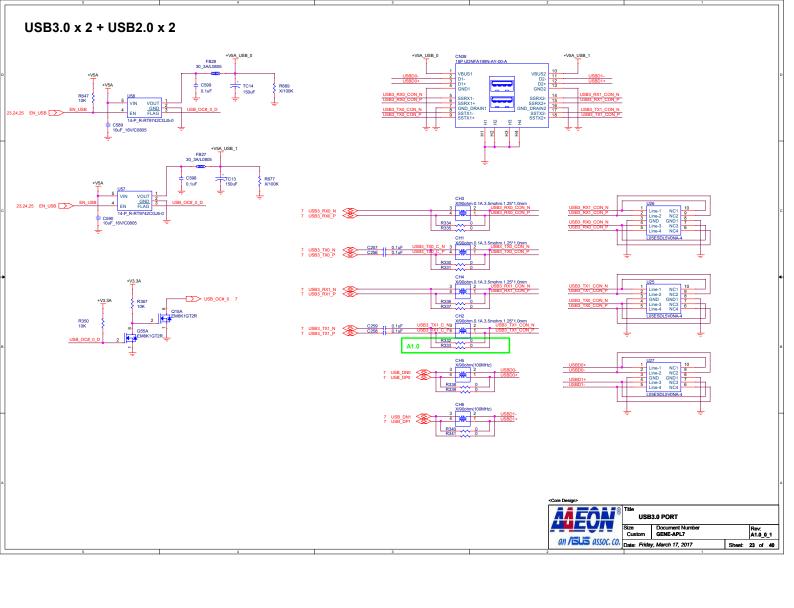


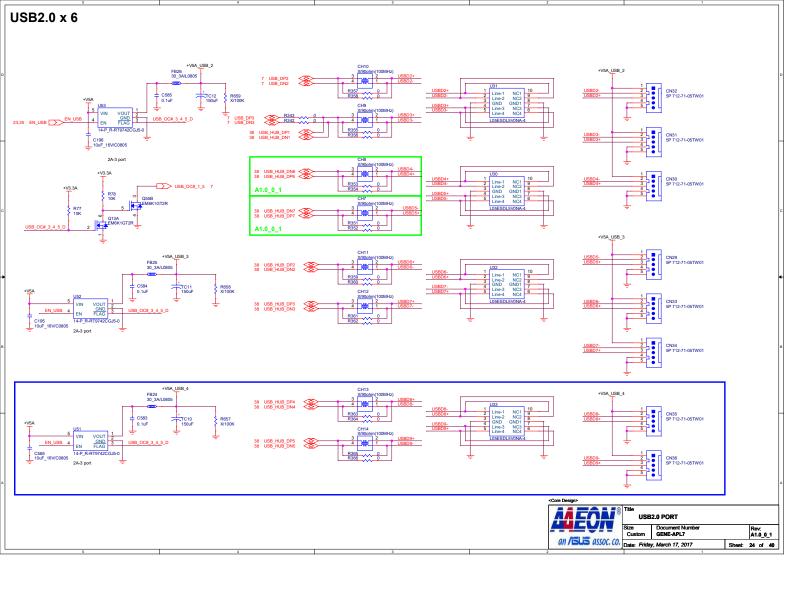


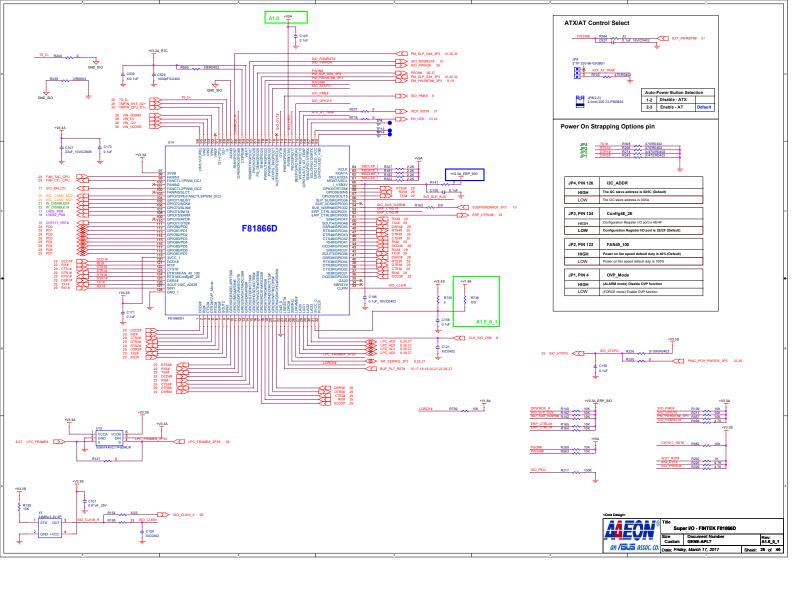


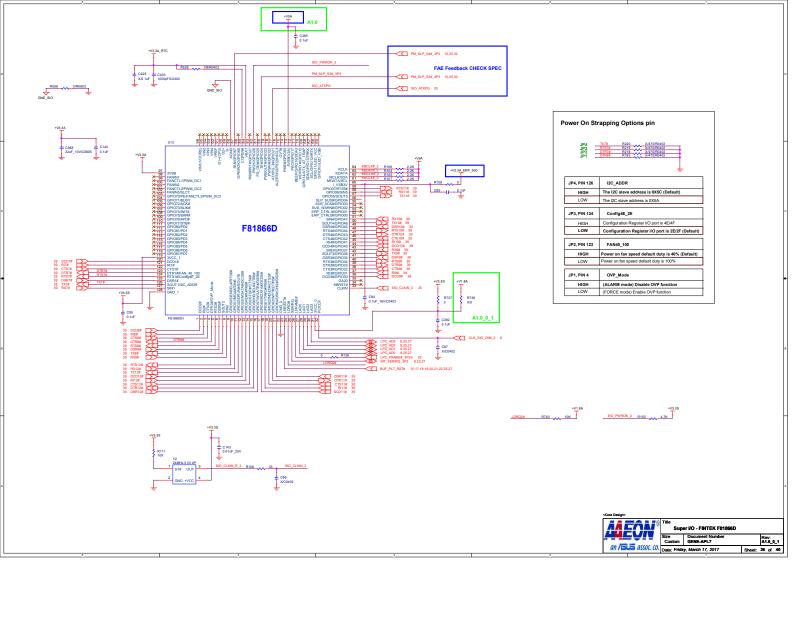


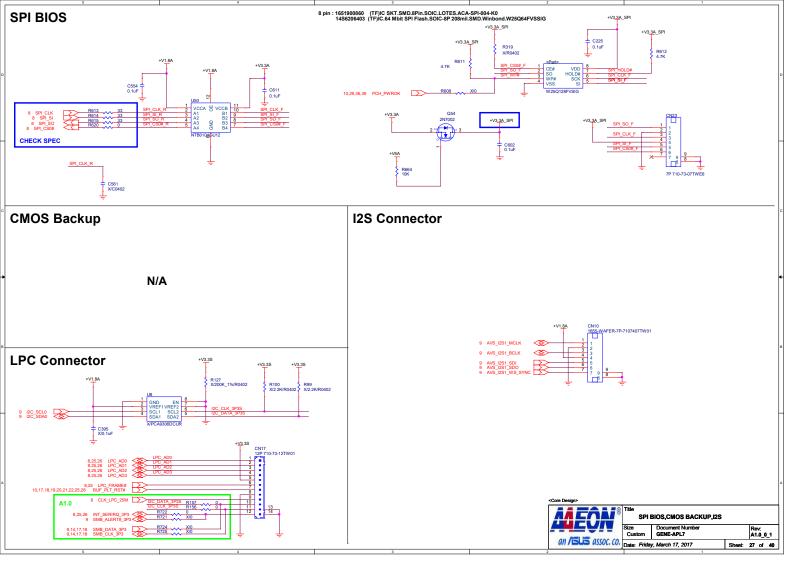
7,22 SATA\_TXN1 7,22 SATA\_TXP1

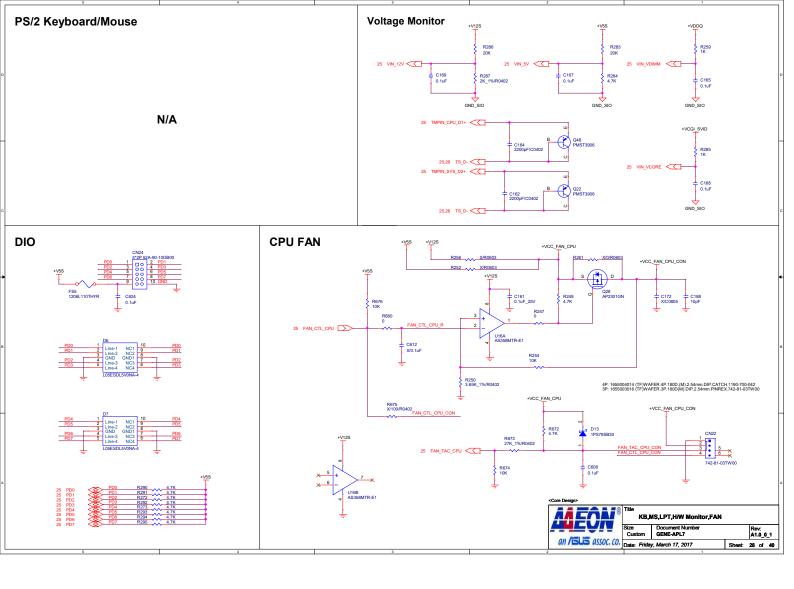


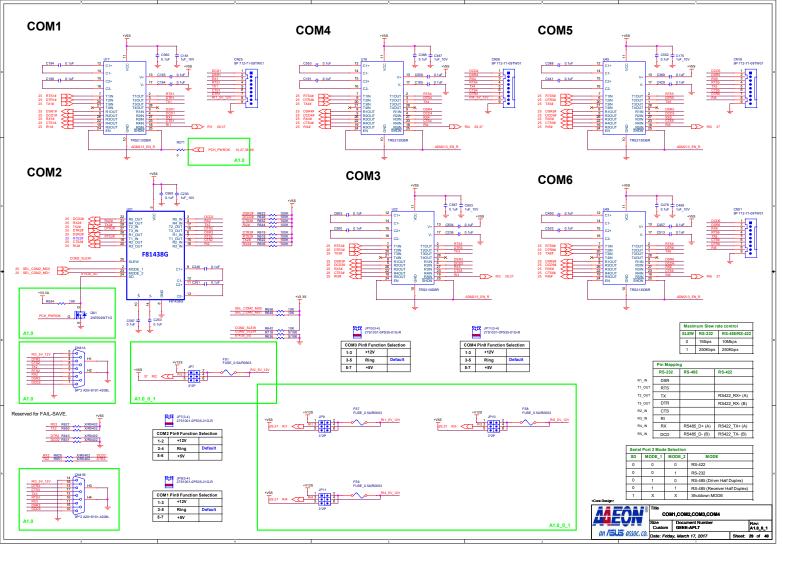


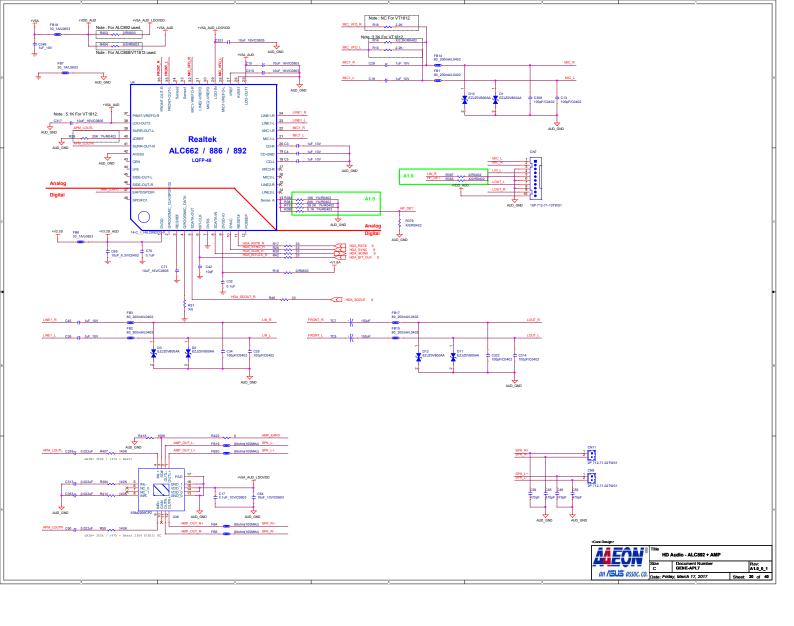


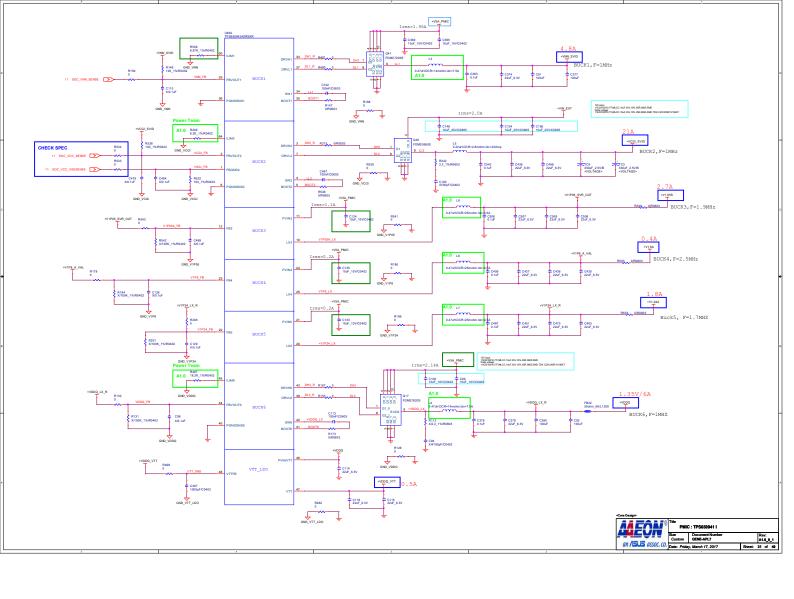




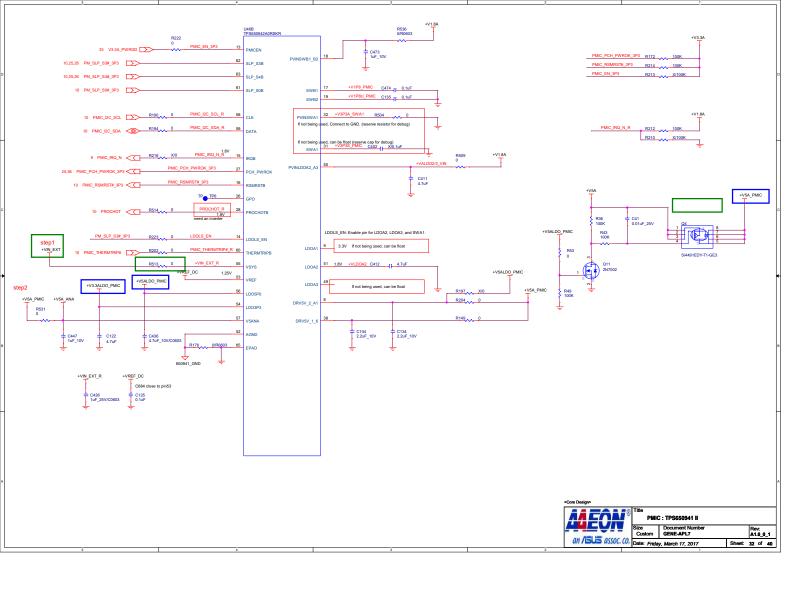


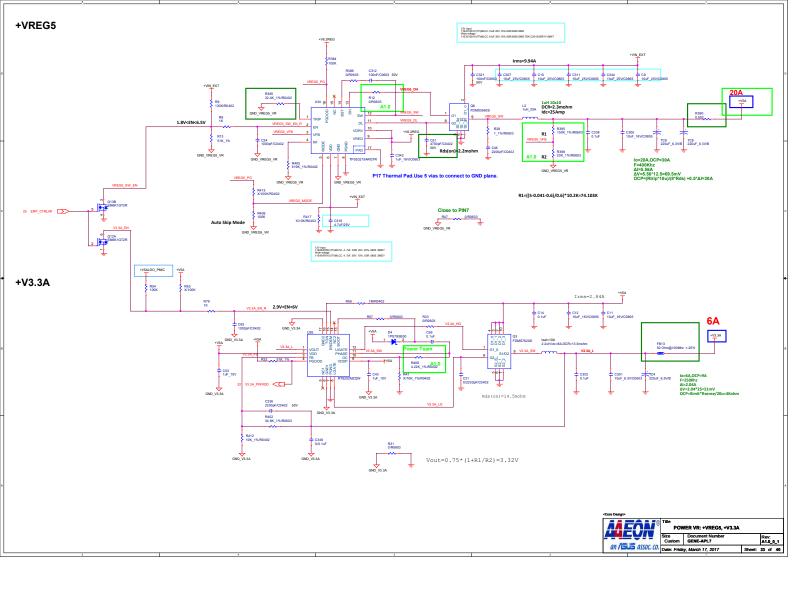






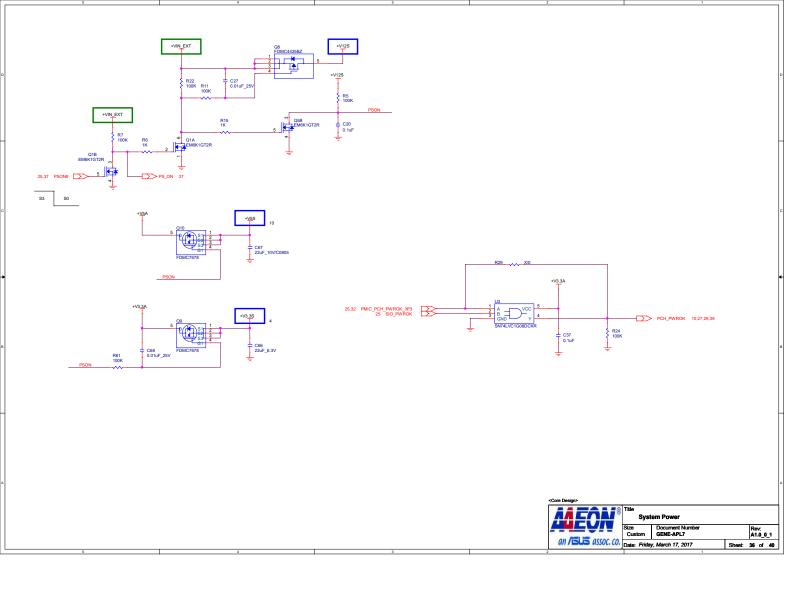
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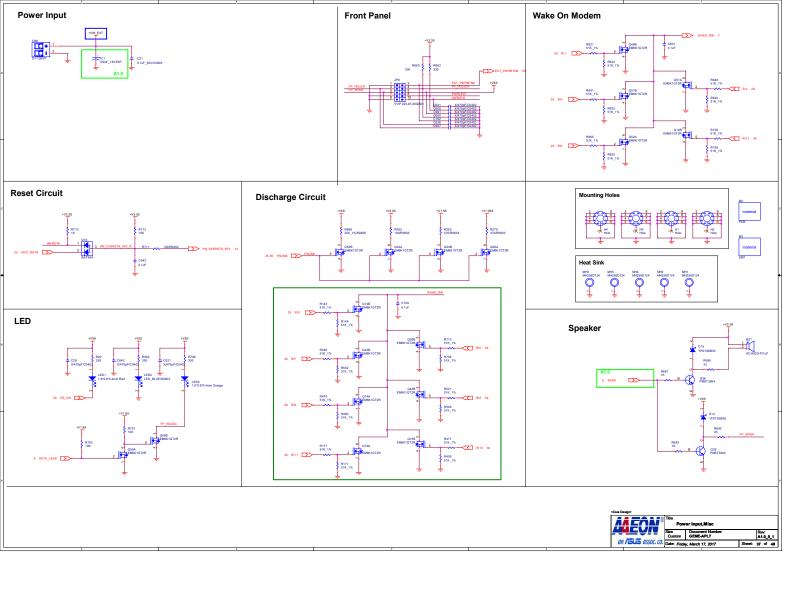


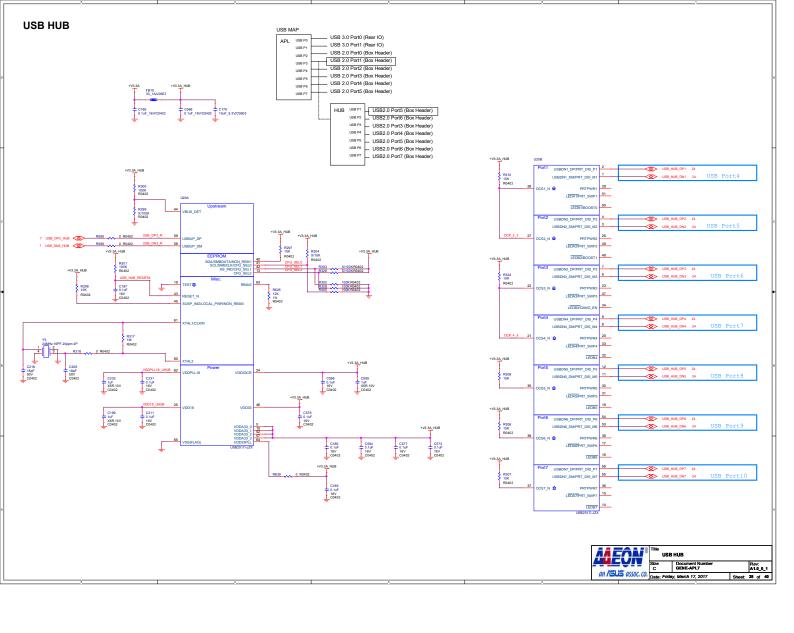


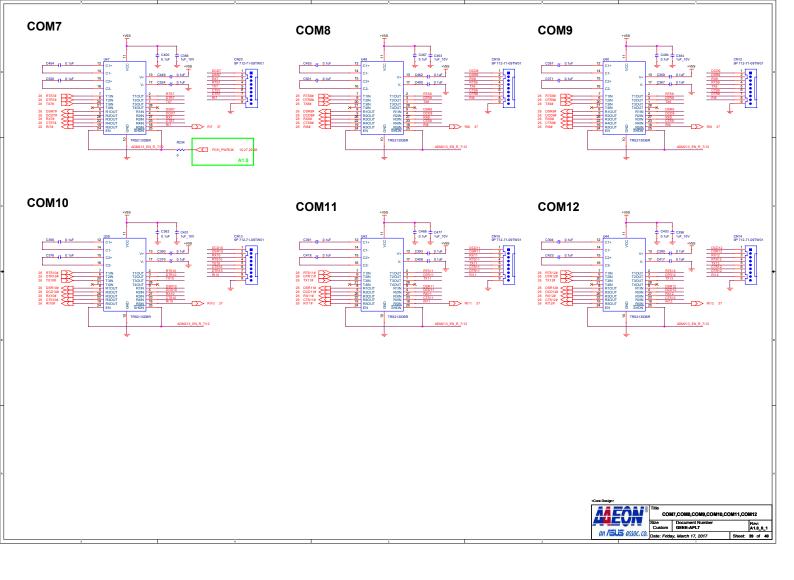
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## HISTORY

tem	Date	Revision	Page	Modification List	Reason
1	2016/09/12	A0.1		First Release	Release and follow GENE-APL5 A0.2 modify lists.
1	2016/12/13	A1.0	06	DDI1_TXP_1_L, DDI1_TXN_1_L, DDI1_TXP_0_L, DDI1_TXN_0_L DSN modifications	R&D Internal modifications
			09	GPIO_PWRBTN# DSN modifications	R&D Internal modifications (APL team suggest)
			09	Add Q43A, R723 for SMB_ALERT#_3P3	R&D Internal modifications (ECD expert suggest)
			10	D5, D8, D9 change the part number to 1301793040	R&D Internal modifications
			16	eDP PNL1_BKLTEN_3P3, PNL1_BKLTCTL_3P3 level shifter Q62, Q63	R&D Internal modifications
			18	C33, C38 for DDI1_AUXN and DDI1_AUXP	R&D Internal modifications
			18	R430 for DDI1_HPD	R&D Internal modifications
			21	Add CN18 for uSIM	R&D Internal modifications
			21	Add R720 for PCIE_CLKRQ2#_MPCIE	R&D Internal modifications
			22	Add R719 for PCIE_CLKRQ3#_MPCIE	R&D Internal modifications
			25	U14 PIN 5VSB modifications to +V5A	R&D Internal modifications
			26	U13 PIN 5VSB modifications to +V5A	R&D Internal modifications
			27	CN17 add SMB_ALERT#_3P3, SMB_DATA_3P3, SMB_CLK_3P3	R&D Internal modifications
			29	CN41 modifications to pin define	R&D Internal modifications
			29	Add Q61 for 81438_SD pin	R&D Internal modifications
			29	R271 modifications to PCH_PWROK	R&D Internal modifications
			30	Add R733 and LIN_R	R&D Internal modifications
			31	Change R209 from 5.6K to 8.2Kohm(1050508224) for OCP adjust.	Power Team
			31	Change R497 from 10.2K to 18.2Kohm(105A518223) for OCP adjust.	Power Team
			31	L6, L7, L8 change to 121110477B	R&D Internal modifications(Cost)
			31	L4, change to 121110477A	R&D Internal modifications(Cost)
			32	R12 change to 0ohm(105A700004) for Dead time adjust.	Power Team
			33	R395, R399 change to 150K and 20K for Vout adjust.	Power Team
			37	TC1 chanhe to 1181610196	R&D Internal modifications
			39	R234 change to netname to PCH PWROK	R&D Internal modifications